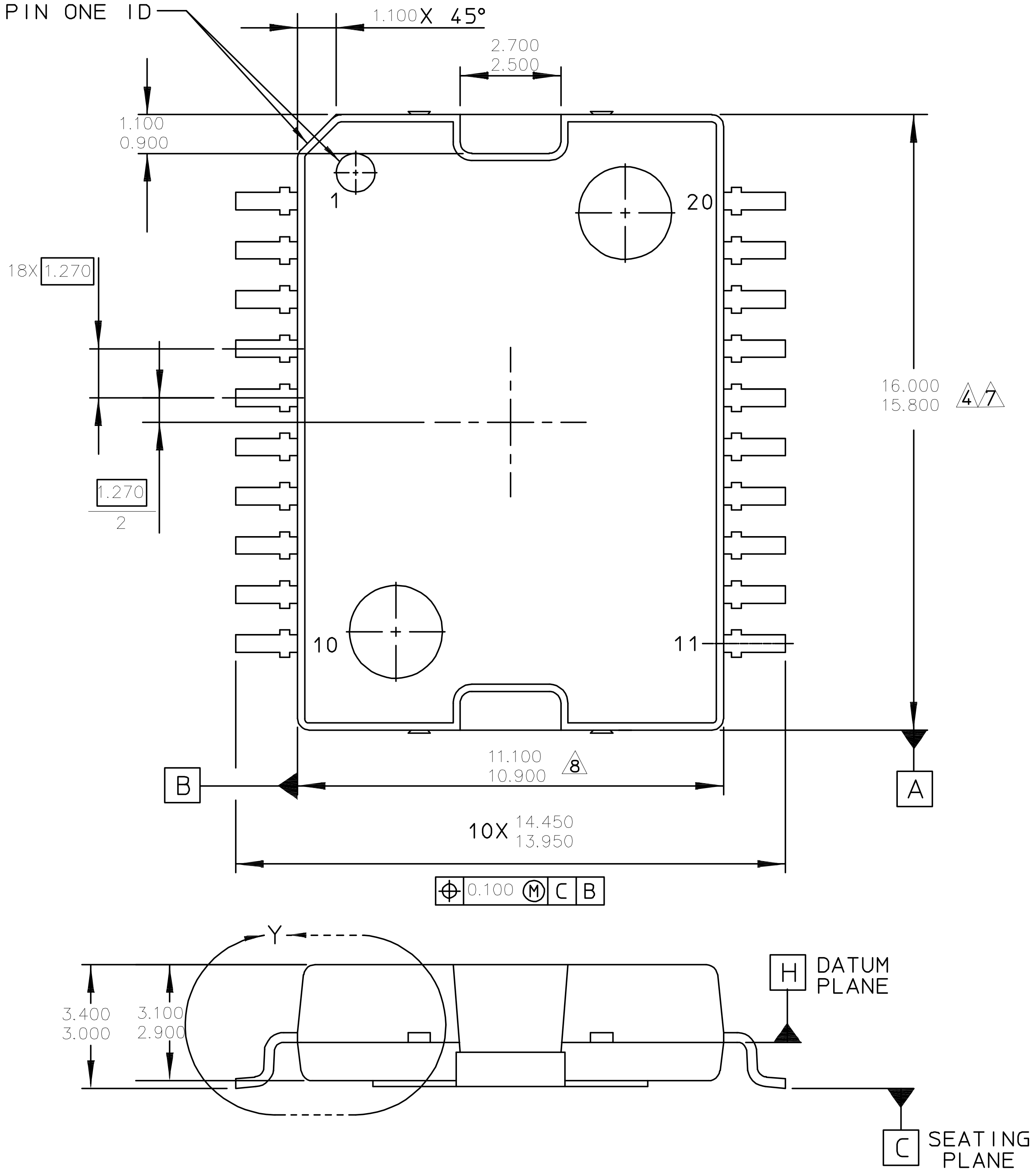


© NXP SEMICONDUCTORS N.V. ALL RIGHTS RESERVED	MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE

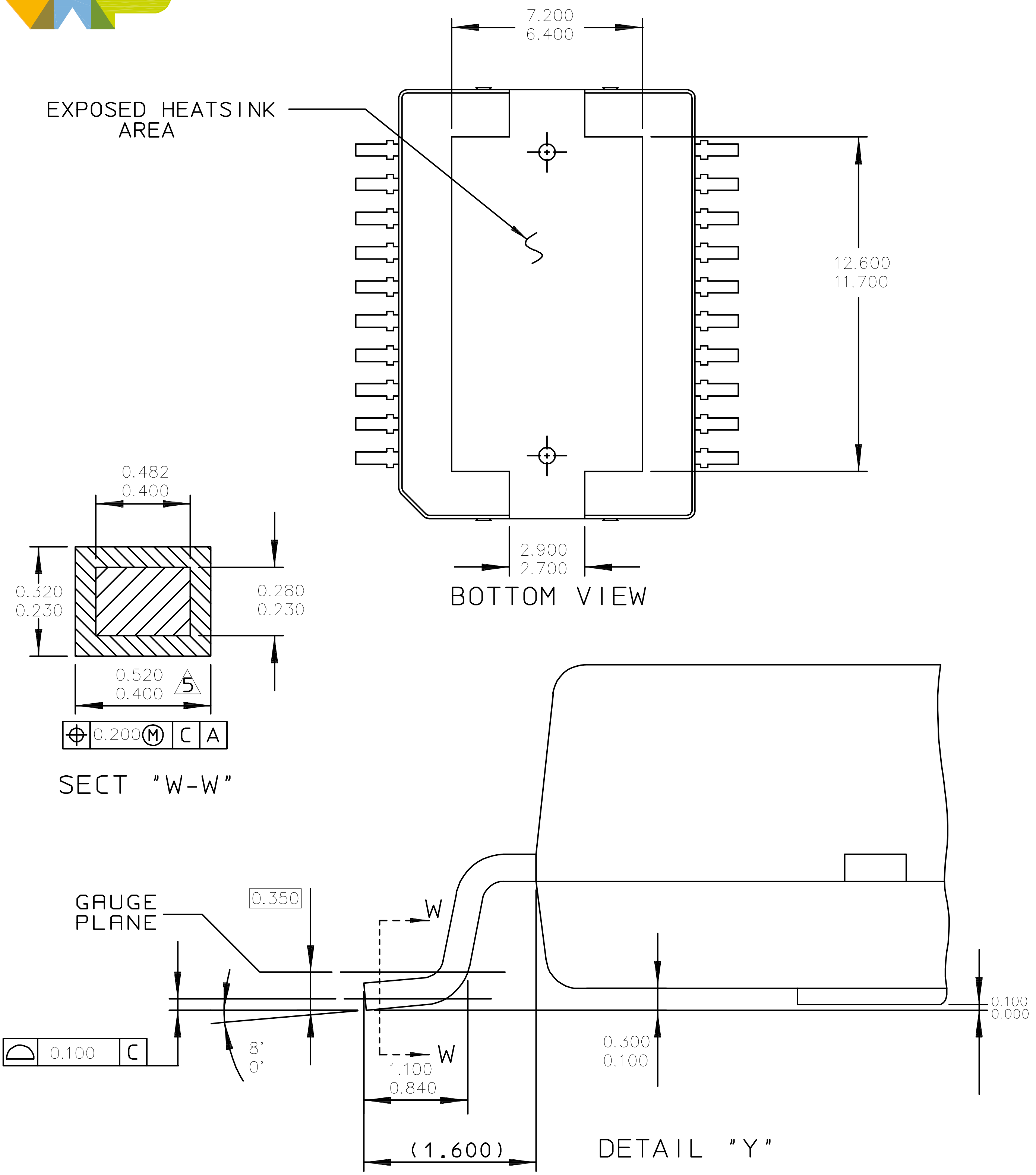
TITLE:

20 LEAD HSOP
W/PROTRUDING HEATSINK

DOCUMENT NO: 98ASH70702A REV: D

STANDARD: NON–JEDEC

SOT397–2 11 MAR 2016


BOTTOM VIEW

SECT "W-W"

DETAIL "Y"

© NXP SEMICONDUCTORS N.V. ALL RIGHTS RESERVED	**MECHANICAL OUTLINE**	PRINT VERSION NOT TO SCALE
TITLE: 20 LEAD HSOP W/PROTRUDING HEATSINK	DOCUMENT NO: 98ASH70702A REV: D	
	STANDARD: NON-JEDEC	
	SOT397-2 11 MAR 2016	

NOTES:

1. CONTROLLING DIMENSION: MILLIMETER.

2. DIMENSIONS AND TOLERANCES PER ASME Y14.5M—1994.

3. DATUM PLANE H IS LOCATED AT BOTTOM OF THE LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE BOTTOM OF THE PARTING LINE.

△4. THIS DIMENSION DOES NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION IS 0.150 PER SIDE. THIS DIMENSION DOES INCLUDE MOLD MISMATCH AND IS DETERMINED AT DATUM H.

△5. DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION IS 0.127 TOTAL IN EXCESS OF THE DIMENSION AT MAXIMUM MATERIAL CONDITION.

6. DATUM A AND B TO BE DETERMINED AT DATUM PLANE H.

△7. DIMENSION DOES NOT INCLUDE TIEBAR PROTRUSIONS. ALLOWABLE TIEBAR PROTRUSIONS ARE 0.150 PER SIDE.

△8. THIS DIMENSION DOES NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION IS 0.250 PER SIDE. THIS DIMENSION DOES INCLUDE MOLD MISMATCH AND IS DETERMINED AT DATUM H.

MECHANICAL OUTLINE

PRINT VERSION NOT TO SCALE

TITLE:
20 LEAD HSOP
W/PROTRUDING HEATSINK

DOCUMENT NO: 98ASH70702A REV: D

STANDARD: NON JEDEC

SOT397—2 11 MAR 2016